
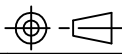


CIRCUITS	DIM. A	DIM. B	DIM. C
16	14.60	7.62	10.16
20	18.03	7.62	10.16
24	21.55	7.62	10.16
28	25.20	10.16	12.70
30	27.00	10.16	12.70
40	35.90	15.24	17.78
42	37.70	15.24	17.78
48	43.10	15.24	17.78
52	46.60	15.24	17.78
56	50.00	15.24	17.78
64	57.20	19.05	21.59

- MATERIAL & FINISH**
- * CONTACT: BE CU
PLATING: 10 MICRO INCH GOLD
 - * SLEEVE: BRASS
PLATING: G=10 MICRO INCH GOLD
T=200 MICRO INCH TIN
 - * INSULATOR: GLASS FILLED POLYESTER, UL 94V-0
 - * INSERTION FORCE: AVERAGE 500 GR
 - * EXTRACTION TEST: AVERAGE 159 GR
 - * RESIST TO SOLDERING HEAT: MAX. 260°C, 5 SEC.
 - * CONTACT RESIST: < = 100M OHMS
 - * INSULATOR RESIST: > = 5000M OHMS
 - * DIELECTRIC WITHSTANDING: 600 VRMS
 - * TEMPERATURE: -55°C TO + 125°C

 易昕企業有限公司 LEAMAX ENTERPRISE CO., LED.				
PROJ		SCALE : F DO NOT SCALE DWG	MOLD NO 2121-1	
APP		93.10.13	MODEL	FILE NO
CHK	CCJ	90.10.25	1.778mm	IC SOCKET 圓孔 PIN
DGN	AMY	90.10.25	UNIT	REV. X1
DRW	SHIEH	90.10.25	MM	SHT 1 OF 1 SIZE A4